



中国科学院
CHINESE ACADEMY OF SCIENCES

Overview of the Back-End Design of Digital Chips

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1. Overview of the Back-end

2. Logical synthesis

3. Timing analysis

4. Place & Route

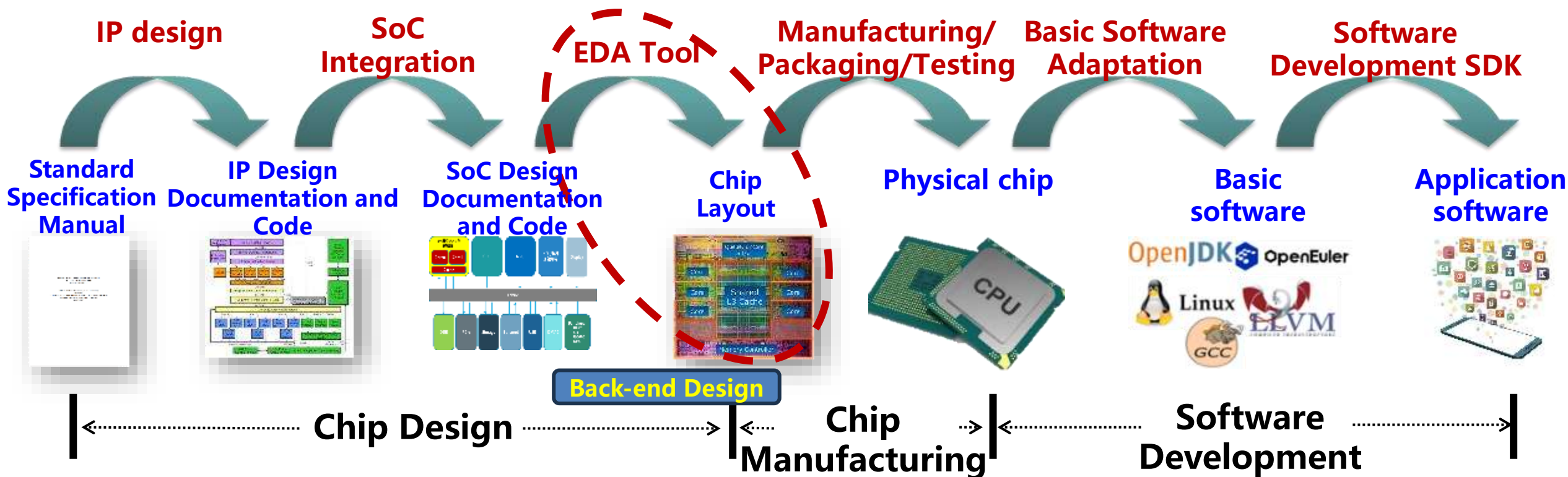
5. Physical verification

1. Overview of the Back-end

■ **Digital chip design**: Translating functional requirements into manufacturable silicon chip circuits

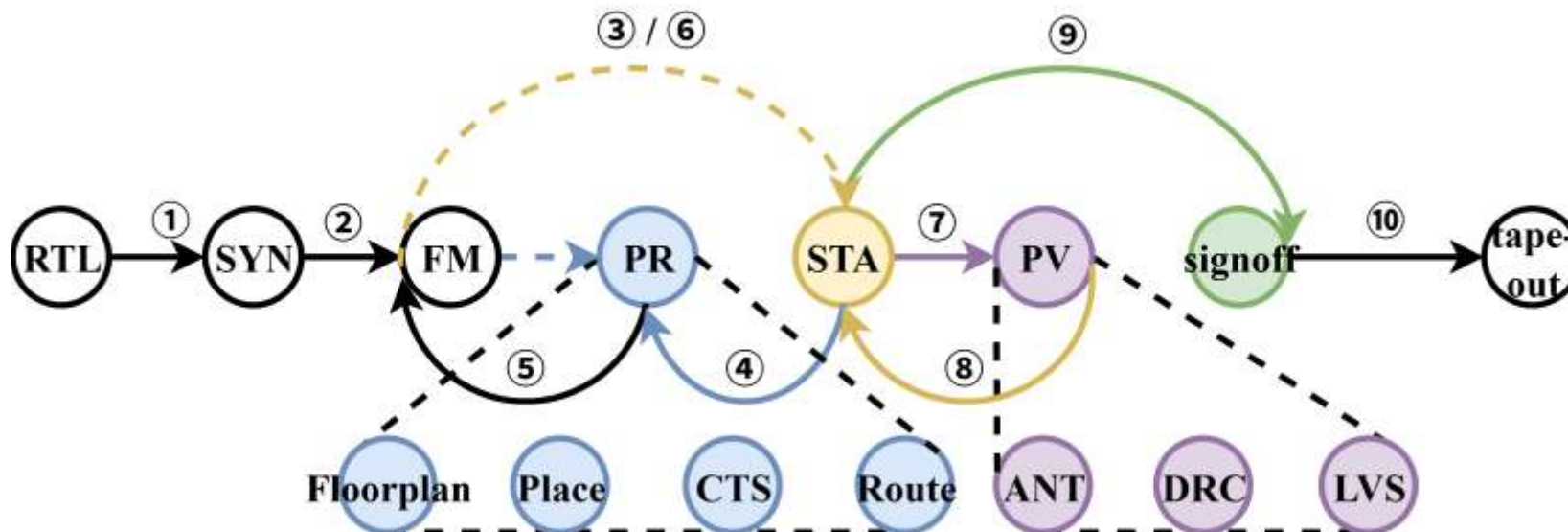
■ Front-end design: Design and verification of RTL

■ **Back-end design: From RTL (Netlist) to the generation of GDS**



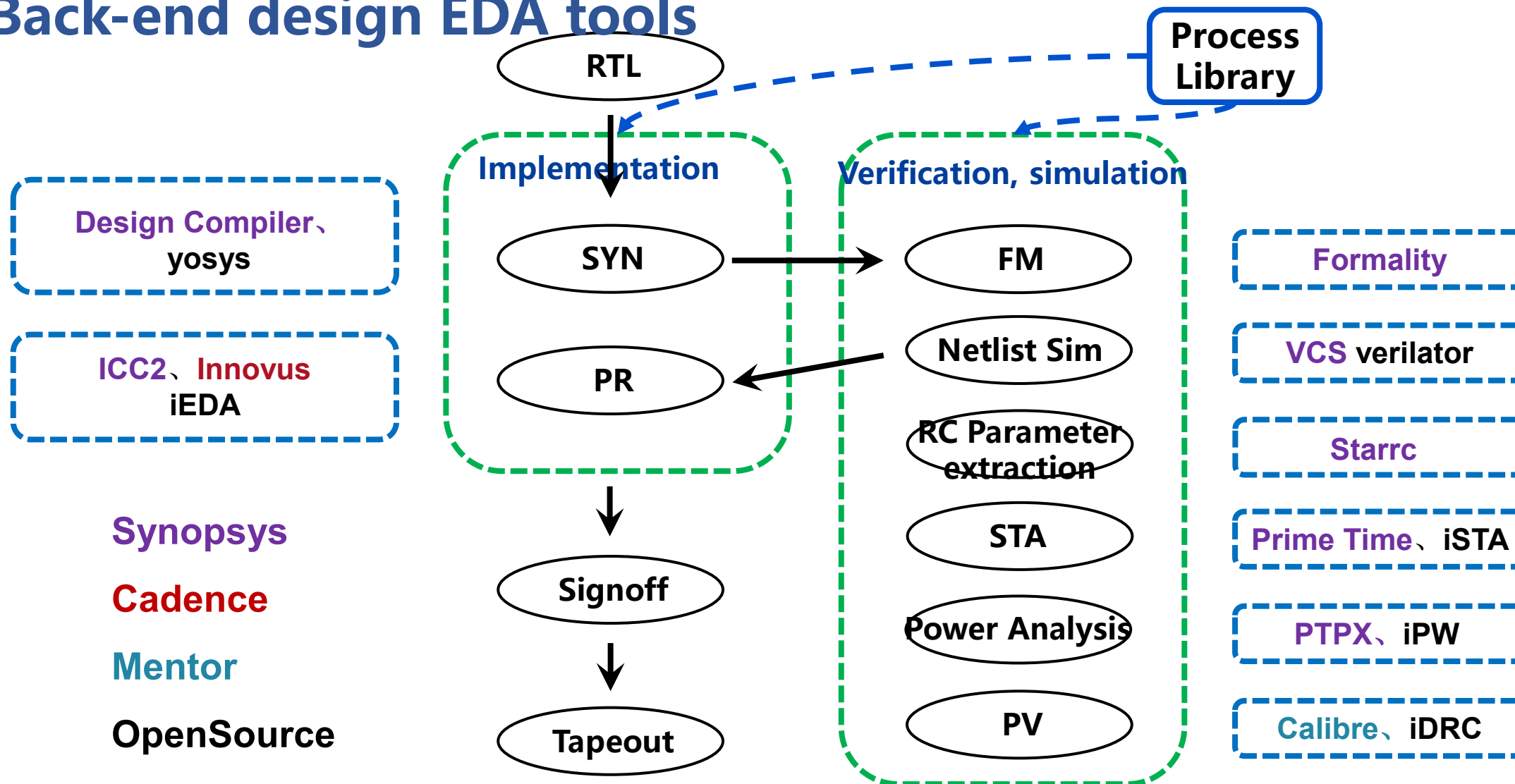
■ Back-end design process

- Logical synthesis (SYN)
- Formal verification (FM)
- Static timing analysis (STA)
- Place & Route (PR)
 - Floorplan
 - Place
 - CTS
 - Route
- Physical verification (PV)
 - ERC
 - DRC
 - LVS
- Signoff
- Tape out



1. Overview of the Backend

■ Back-end design EDA tools



1. Overview of the Backend

■ ECOS (EDA、Chip、One-Student-One-Chip、System)

SoC Template
Select SoC template from the IP Market



Float Panel System
Support the dragging, resizing operations and customized data




Advanced eXtensible Layout Editor



Cloud-based Agile EDA Platform
iEDA Inside
"An open-source EDA infrastructure"
(support IC555/SKY130/IHP130)

ECOS Studio
"Componentization of Data"



Real-time Collaboration*



Flow

Architecture
RTL/Verify
Backend

Pipeline Mode

*: this feature will be released in 2025Q4

Synthesis Flow



Dashboard



Merge to Latest Shuttle



1. Overview of the Backend

- Supports one-stop RISC-V processor SoC chip design and tape-out using open-source EDA tools, open-source IP, and open-source PDK

Submit Design

(Processor core/IP/...)

```
1 module ysyx_23060171_idu(  
2   input [6:0]opcode,  
3   input [2:0]f3,  
4   input [6:0]f7,  
5   output [2:0]alucontrol,  
6   output Regwrite,  
7   output [2:0]immtype  
8 );  
9   assign alucontrol = 3'b000;  
10  assign Regwrite = 1;  
11  assign immtype = 3'b000;  
12 endmodule
```



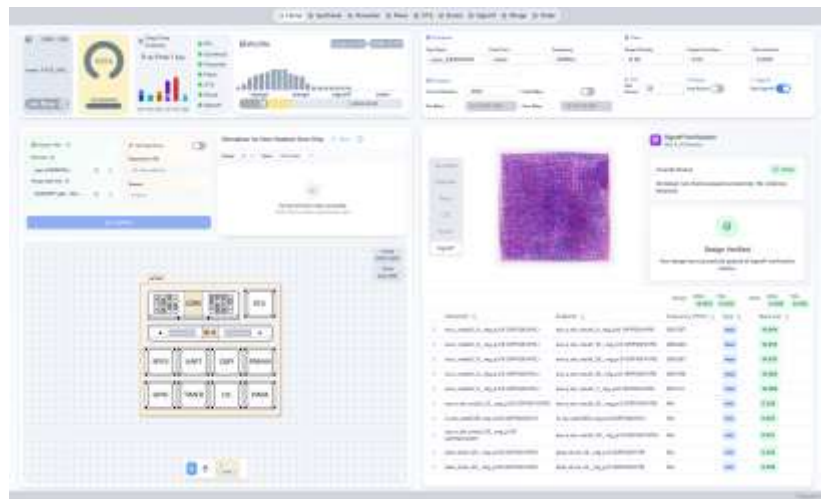
Home delivery

(Chip + Board)

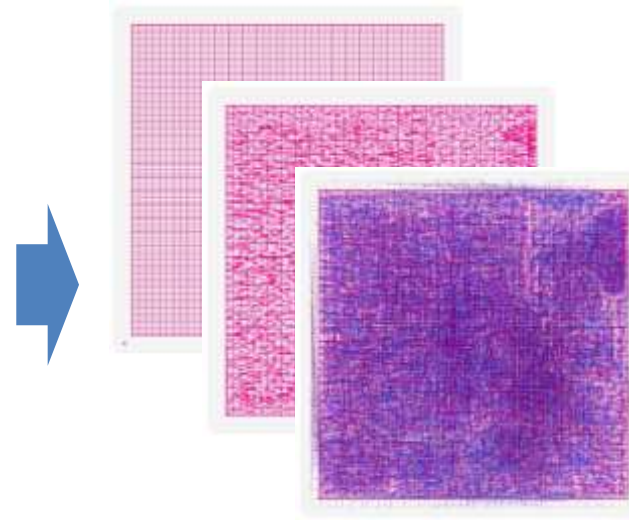


1. Overview of the Backend

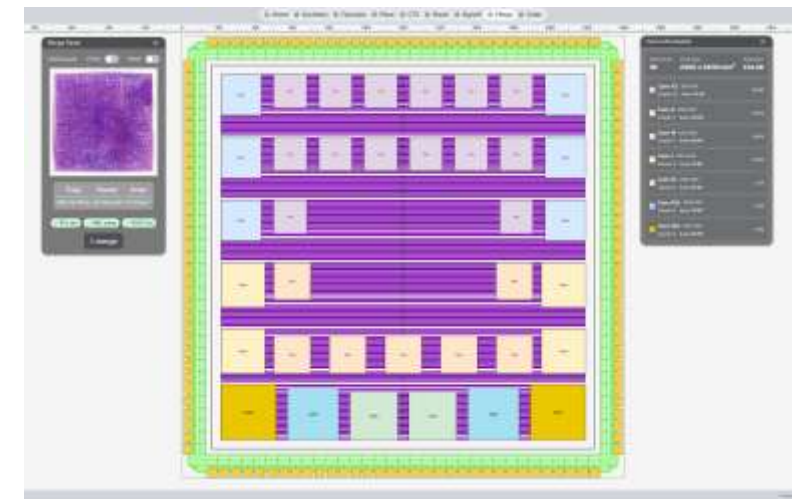
- Supports end-to-end layout design of 100,000 instances of chips from RTL to GDSII on ICsprout 55nm process



Home interface



Layout render effect

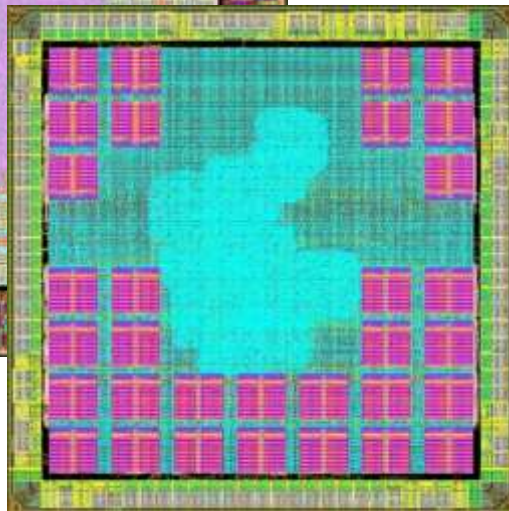
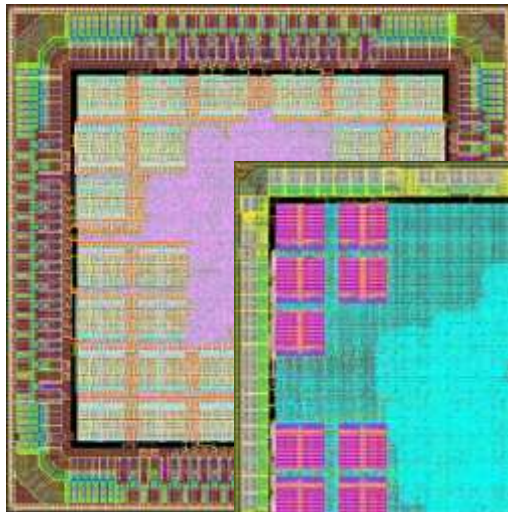


Merge interface



1. Overview of the Backend

- Two chips designed based on ICsprout 55nm process have been fabricated and are running successfully



Design: A RV32IMAC SoC(PSRAM, QSPI, UART, I2C, PWM, TIMER, RNG).
Size: 4mm²(128KB OCM, no PLL)

Freq: 100MHz(external clock bypass)
Gates: 1.517M(73,009 cells) Power: 115.4mW(dynamic) 0.42mW(static)

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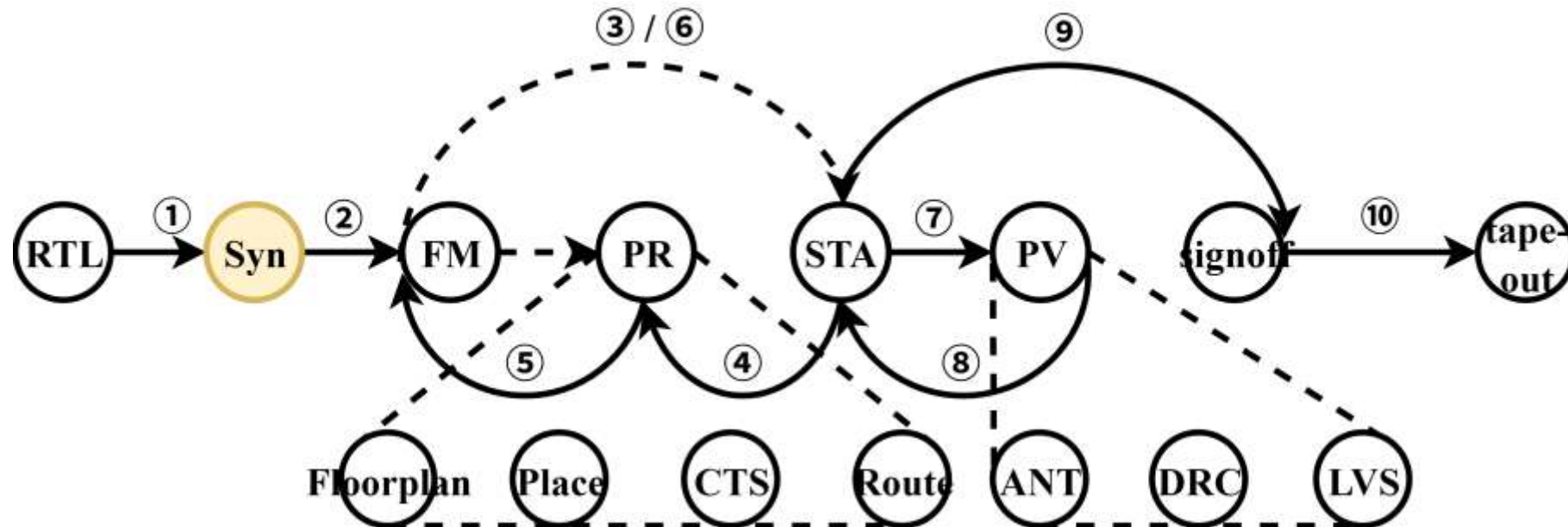
3. Timing analysis

4. Place & Route

5. Physical verification

■ Synthesis (Syn)

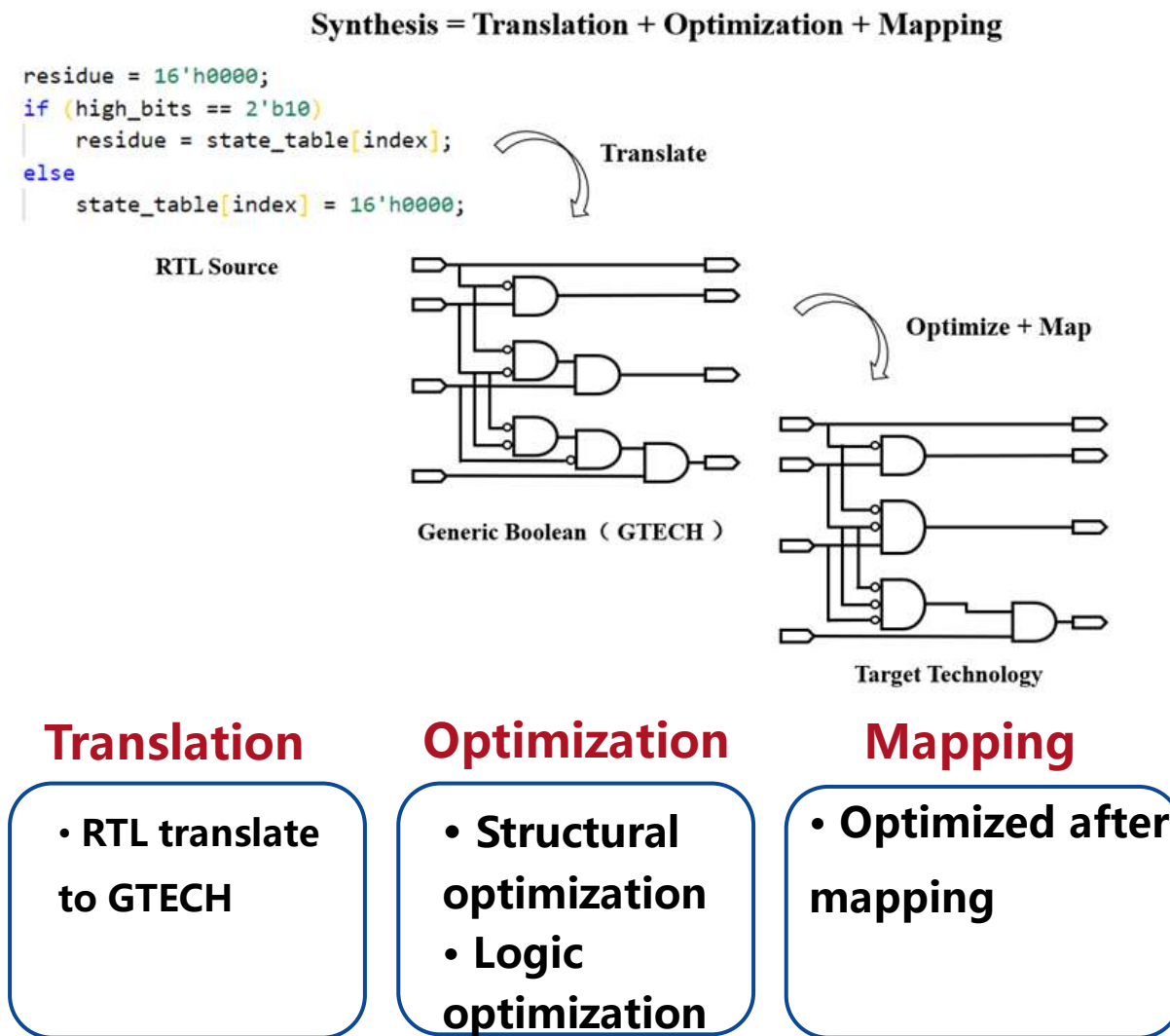
- Synthesis involves mapping the front-end RTL code to a specific process library, adding constraint information, and logically optimizing the RTL code to generate a gate-level netlist. It is the process from **RTL** to **Gate-Level Netlist**



■ Synthesis : RTL to Gate-level Netlist generation

■ Input file:

- RTL Code (Verilog、VHDL)
- Library files (.lib/.db)
- Constraint files (.sdc)



■ Comparison of the RTL and Netlist files

```
1  module asic_top(  
2      input clock,  
3      input reset,  
4      input in,  
5      output out  
6  );  
7  
8  reg reg_in;  
9  reg reg_out;  
10  
11  always @(posedge clock or posedge reset)  
12  begin  
13      if (reset)begin  
14          reg_in  <= 1'b0;  
15          reg_out <= 1'b0;  
16      end  
17      else begin  
18          reg_in  <= 1'b1;  
19          reg_out <= reg_in ? in : 1'b0;  
20      end  
21  end  
22  
23  assign out = reg_out;  
24  endmodule
```

RTL

vs

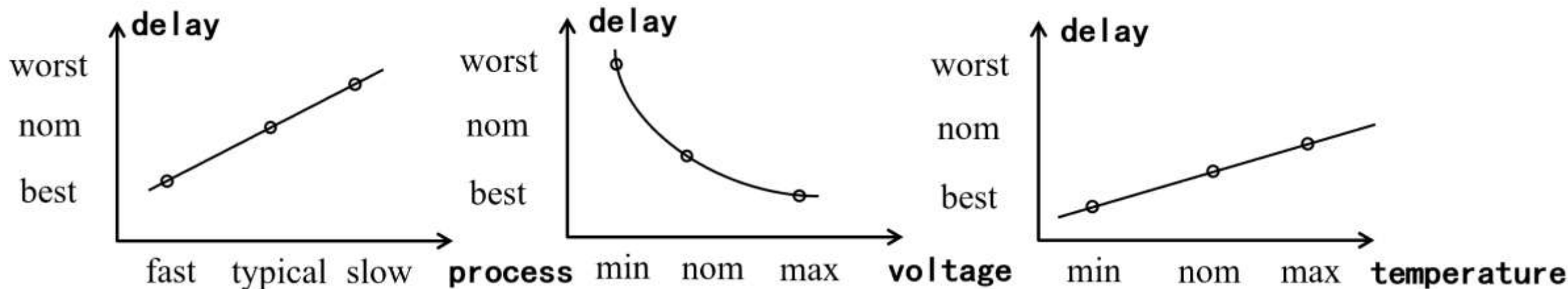
```
1  module asic_top (  
2      clock,  
3      in,  
4      out,  
5      reset  
6  );  
7  
8  input clock ;  
9  input in ;  
10 output out ;  
11 input reset ;  
12  
13 wire _0_ ;  
14 wire _1_ ;  
15 wire _2_ ;  
16 wire clock ;  
17 wire in ;  
18 wire out ;  
19 wire out_reg_p_D ;  
20 wire reg_in ;  
21 wire reset ;  
22  
23 AND2X16H7L _3_ ( .A(reg_in ), .B(in ), .Y(out_reg_p_D ) );  
24 INVX0P5H7L _4_ ( .A(reset ), .Y(_0_ ) );  
25 INVX0P5H7L _5_ ( .A(reset ), .Y(_1_ ) );  
26 TIEIH7H _6_ ( .Y(_2_ ) );  
27 DFFRQX2H7L out_reg_p ( .CK(clock ), .D(out_reg_p_D ), .Q(out ), .RN(_0_ ) );  
28 DFFRQX2H7L reg_in_reg_p ( .CK(clock ), .D(_2_ ), .Q(reg_in ), .RN(_1_ ) );  
29  
30 endmodule
```

standard cell

netlist

■ PVT (Process, Voltage, Temperature)

- The speed of the process Corner, voltage level and temperature level will all affect the timing analysis results



- **BC:** ff_0p88v_m40c:

- fast process
- high power voltage
- low temperature

- **Typical:** typical_0p8v_25c:

- typical process
- normal power voltage
- normal temperature

- **WC:** ss_0p72v_125c:

- slow process
- low power voltage
- high temperature

2. Synthesis

■ Synthesis report

```
≡ asic_top.area.rpt
≡ asic_top.check_design.pre.rpt
≡ asic_top.check_design.rpt
≡ asic_top.check_timing.rpt
≡ asic_top.clock_gating.rpt
≡ asic_top.clock.rpt
≡ asic_top.constraint.rpt
≡ asic_top.dont_touch.rpt
≡ asic_top.drc.rpt
≡ asic_top.power.rpt
≡ asic_top.qor.rpt
≡ asic_top.registers.rpt
≡ asic_top.statistics.rpt
≡ asic_top.timing.rpt
```

```
1 #-----
2 # Area Area (μm²)
3 #-----
4 total      std      mem ipio      sub_harden
5 4219061.4  2221580.0  0.0  1997481.4  0.0
6
7 #-----
8 # Cell Count Design scale
9 #-----
10 total      std      mem ipio      sub_harden
11 182428  182320  0    108    0
12
13 #-----
14 # Vt/Cl ratio(area Device type
15 #-----
16 SVT40  LVT40
17 97.59  2.41
18
19 #-----
20 # Timing Timing
21 #-----
22 group                                org_freq  over_freq  wns      tns      num
23 CLK_u0_chiplink_rx_clk_pad_PAD  25.0      38.5      15.714   0.000   0
24 CLK_u0_clk_XC                    25.0      38.5      2.283    0.000   0
25 CLK_u0_pll_CLK_OUT               100.0     153.8     0.000    0.000   0
26 CLK_u1_clk_XC                    100.0     153.8     0.006    0.000   0
27 CLK_u1_pll_CLK_OUT               100.0     153.8     0.006    0.000   0
```

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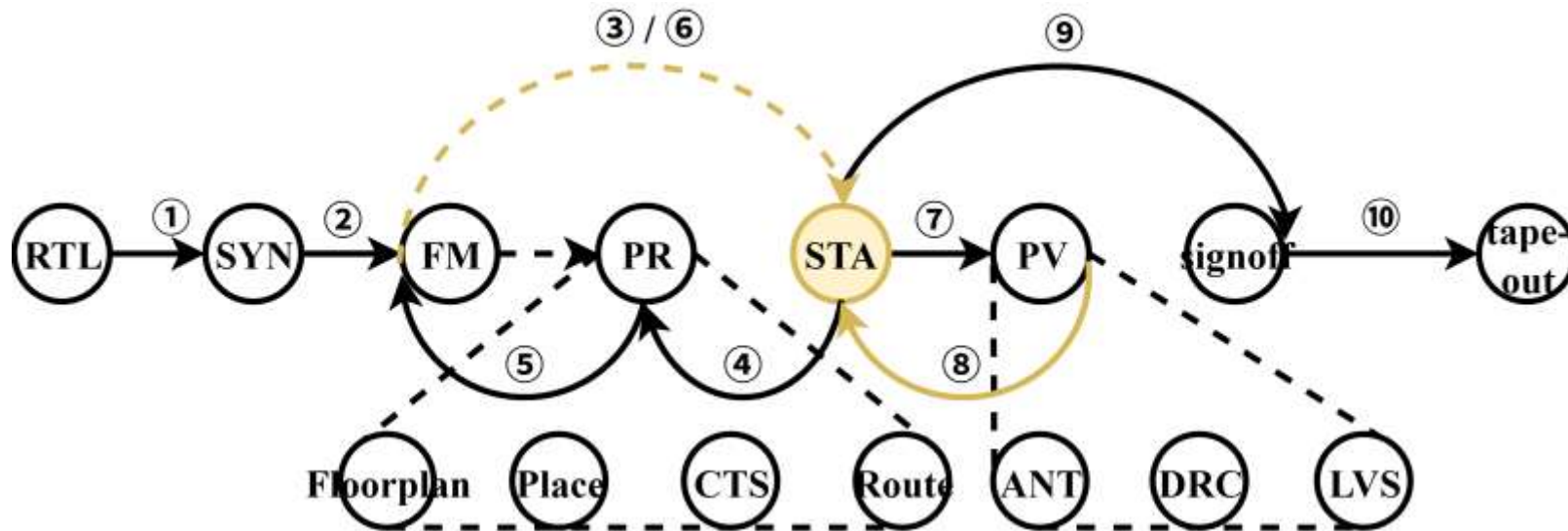
4. Place & Route

5. Physical verification

■ Static Timing Analysis (STA)

■ STA is the method for verifying the circuit timing by checking the timing information of all paths

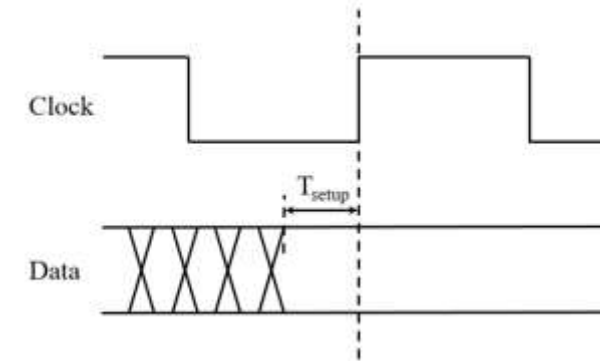
- Divide the design into several paths
- Calculate the delay of each path respectively
- Check whether the delay of each path meets the design constraints



3. Timing Analysis

■ Setup Time (T_{setup})

- T_{setup} is the time when the data remains stable before the rising edge of the clock arrives



- (1) The time when the data reaches the D end of UFF1(arrival time):

$$T_a = T_{\text{launch}} + T_{\text{ck-q}} + T_{\text{logic}}$$

- (2) Meet the maximum time allowed by setup (required time):

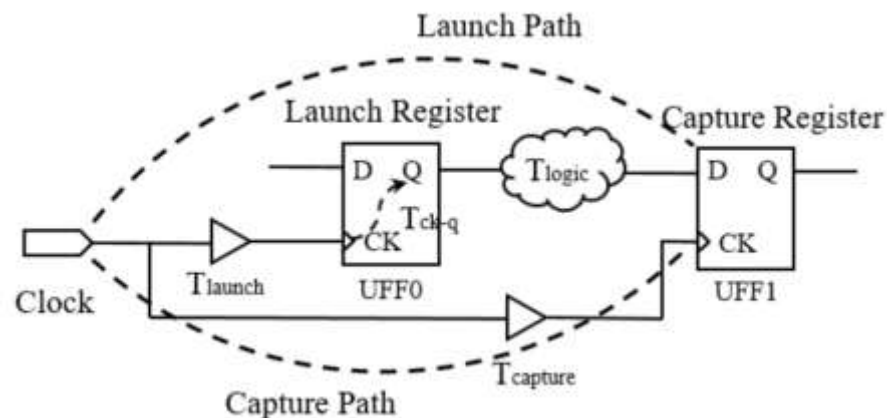
$$T_r = T_{\text{capture}} + T_{\text{clk}} - T_{\text{setup}}$$

- (3) According to the setup time requirements, $T_r - T_a = T_{\text{margin}} \geq 0$

$$T_{\text{capture}} + T_{\text{clk}} - T_{\text{setup}} - T_{\text{launch}} - T_{\text{ck-q}} - T_{\text{logic}} \geq 0$$

- (4) Let $T_{\text{capture}} - T_{\text{launch}} = T_{\text{skew}}$, and we get:

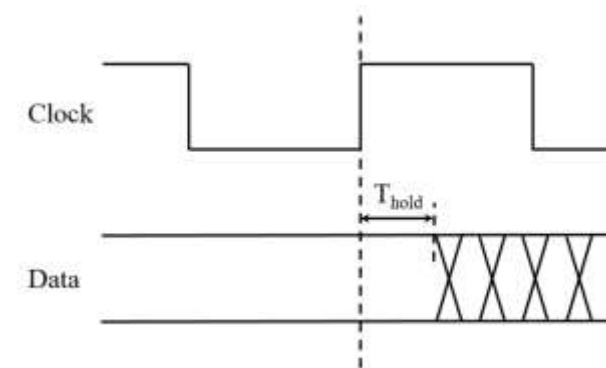
$$T_{\text{skew}} + T_{\text{clk}} \geq T_{\text{setup}} + T_{\text{ck-q}} + T_{\text{logic}}$$



3. Timing Analysis

■ Hold Time (T_{hold})

■ T_{hold} is the time when the data remains stable after the rising edge of the clock arrives



(1) The time when the data reaches the D end of UFF1(arrival time) :

$$T_a = T_{\text{launch}} + T_{\text{ck-q}} + T_{\text{logic}}$$

2) Meet the maximum time allowed by hold (required time):

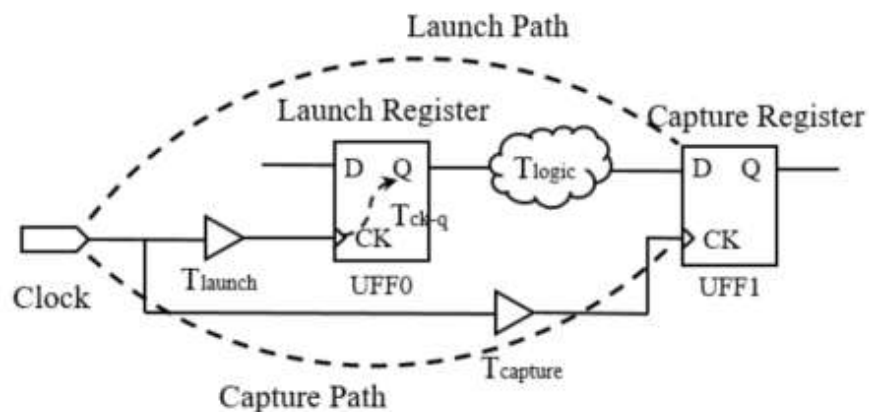
$$T_r = T_{\text{capture}} + T_{\text{hold}}$$

3) According to the hold time requirements, $T_a - T_r = T_{\text{margin}} \geq 0$

$$T_{\text{launch}} + T_{\text{ck-q}} + T_{\text{logic}} - T_{\text{capture}} - T_{\text{hold}} \geq 0$$

(4) Let $T_{\text{capture}} - T_{\text{launch}} = T_{\text{skew}}$, and we get:

$$T_{\text{skew}} + T_{\text{hold}} \leq T_{\text{ck-q}} + T_{\text{logic}}$$



■ Timing violation repair

- Method for fixing T_{setup} timing violations:

$$T_{\text{skew}} + T_{\text{clk}} \geq T_{\text{setup}} + T_{\text{ck-q}} + T_{\text{logic}}$$

- (1) Increase T_{clk} : Reduce frequency
- (2) Reduce T_{logic} : Optimize combinatorial logic, divide the pipeline, and reduce the load on the critical path
- (3) Reduce $T_{\text{ck-q}}$: Switch to faster logic units, such as HVT->LVT

- Method for fixing T_{hold} timing violations:

$$T_{\text{skew}} + T_{\text{hold}} \leq T_{\text{ck-q}} + T_{\text{logic}}$$

- (1) Increase T_{logic} : Increase the delay of the combined path and insert the buffer
- (2) Reduce T_{skew} : Even adopt a negative skew.

3. Timing Analysis (T_{setup})

Point	Incr	Path
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_my_ifu.curr_state_1_reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	0	0
clock network delay (ideal)	0.000	0.000
ysyx_2025_my_ifu.curr_state_1_reg_p:CK (DFFQX1H7L)	0.000	0.000r
ysyx_2025_my_ifu.curr_state_1_reg_p:Q (DFFQX1H7L)	0.089	0.089r
ysyx_2025_my_ifu.curr_state_1_ (net)		
ysyx_2025_my_ifu.curr_state_1_BUF8H7L_A:A (BUF8H7L)	0.000	0.089r
ysyx_2025_my_ifu.curr_state_1_BUF8H7L_A:Y (BUF8H7L)	0.054	0.144r
mepc_7_INVX0P5H7L_A_Y_MUX2X0P5H7L_A_B_AOI21X0P5H7L_Y_A0_NOR2BX1P4H7L_Z_AN (net)		
.....		
ysyx_2025_gpr.rf[8]_18_reg_p_D_NOR2BX8H7L_Z:AN (NOR2BX8H7L)	0.000	1.738f
ysyx_2025_gpr.rf[8]_18_reg_p_D_NOR2BX8H7L_Z:Z (NOR2BX8H7L)	0.034	1.772f
ysyx_2025_gpr.rf[8]_18_reg_p_D (net)		
ysyx_2025_gpr.rf[8]_18_reg_p:D (DFFQX1H7L)	0.000	1.772f
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_gpr.rf[8]_0_reg_p_CK_ICGX0P5H7L_ECK:CK (ICGX0P5H7L)	0.000	0.000r
ysyx_2025_gpr.rf[8]_0_reg_p_CK_ICGX0P5H7L_ECK:ECK (ICGX0P5H7L)	0.000	0.000r
ysyx_2025_gpr.rf[8]_0_reg_p_CK (clock net)		
ysyx_2025_gpr.rf[8]_18_reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	10	10
clock network delay (ideal)	0.000	10.000
ysyx_2025_gpr.rf[8]_18_reg_p:CK (DFFQX1H7L)		10.000r
library setup time	-0.049	9.951
clock reconvergence pessimism	0.000	9.951
path cell delay		1.772(100.000%)
path net delay		0.000(0.000%)
data require time		9.951
data arrival time		1.772
slack (MET)		8.179

slack = $T_r - T_a = 9.951 - 1.772 = 8.179 > 0$, The timing meets the requirements.

3. Timing Analysis (T_{hold})

Point	Incr	Path
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_my_lsu.en_flash_0__reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	0	0
clock network delay (ideal)	0.000	0.000
ysyx_2025_my_lsu.en_flash_0__reg_p:CK (DFFQX1H7L)	0.000	0.000r
ysyx_2025_my_lsu.en_flash_0__reg_p:Q (DFFQX1H7L)	0.064	0.064f
ysyx_2025_my_lsu.en_flash_0_ (net)		
ysyx_2025_my_lsu.en_flash_1__reg_p:D (DFFQX1H7L)	0.000	0.064f
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_my_lsu.en_flash_1__reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	0	0
clock network delay (ideal)	0.000	0.000
ysyx_2025_my_lsu.en_flash_1__reg_p:CK (DFFQX1H7L)		0.000r
library hold time	-0.008	-0.008
clock reconvergence pessimism	-0.000	-0.008
path cell delay		0.064(100.000%)
path net delay		0.000(0.000%)
data require time		-0.008
data arrival time		0.064
slack (MET)		0.072

$slack = T_a - T_r = 0.064 - (-0.008) = 0.072 > 0$, The timing meets the requirements.

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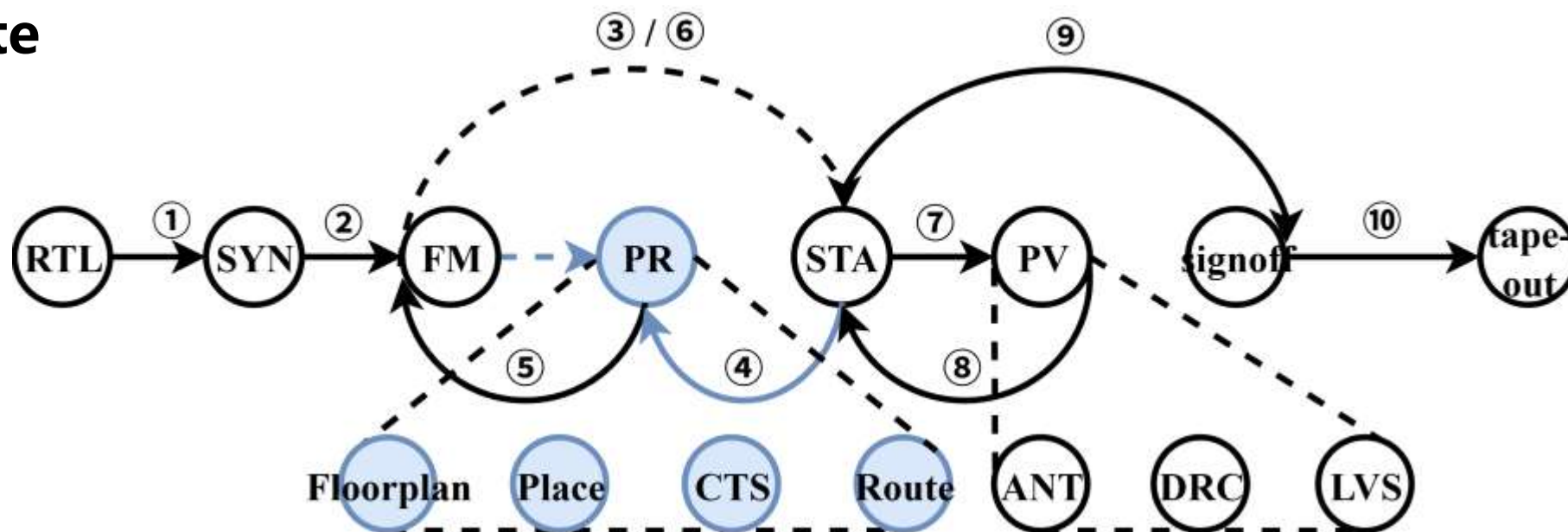
■ Place & Route(PR)

■ Floorplan

■ Place

■ Clock Tree Synthesis(CTS)

■ Route



■ init & Floorplan

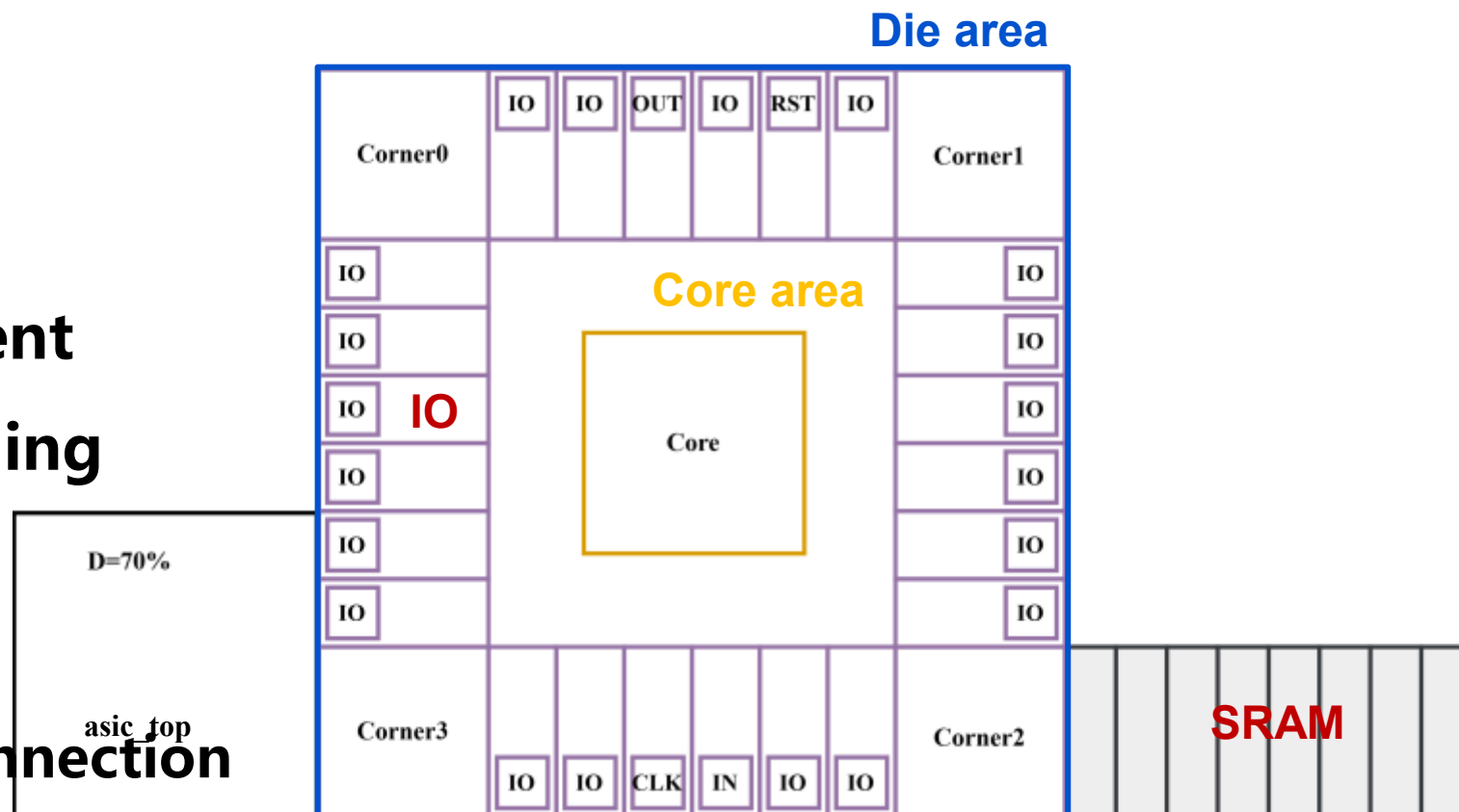
■ Chip design input

■ Chip I/O planning

■ Macro unit placement

■ Power supply planning

- Power ring design
- Power grid design
- Power network connection



Chip utilization rate $D = (\text{Total area of standard units}) / (\text{Core area} - \text{SRAM})$

■ init & Floorplan

■ Chip design input

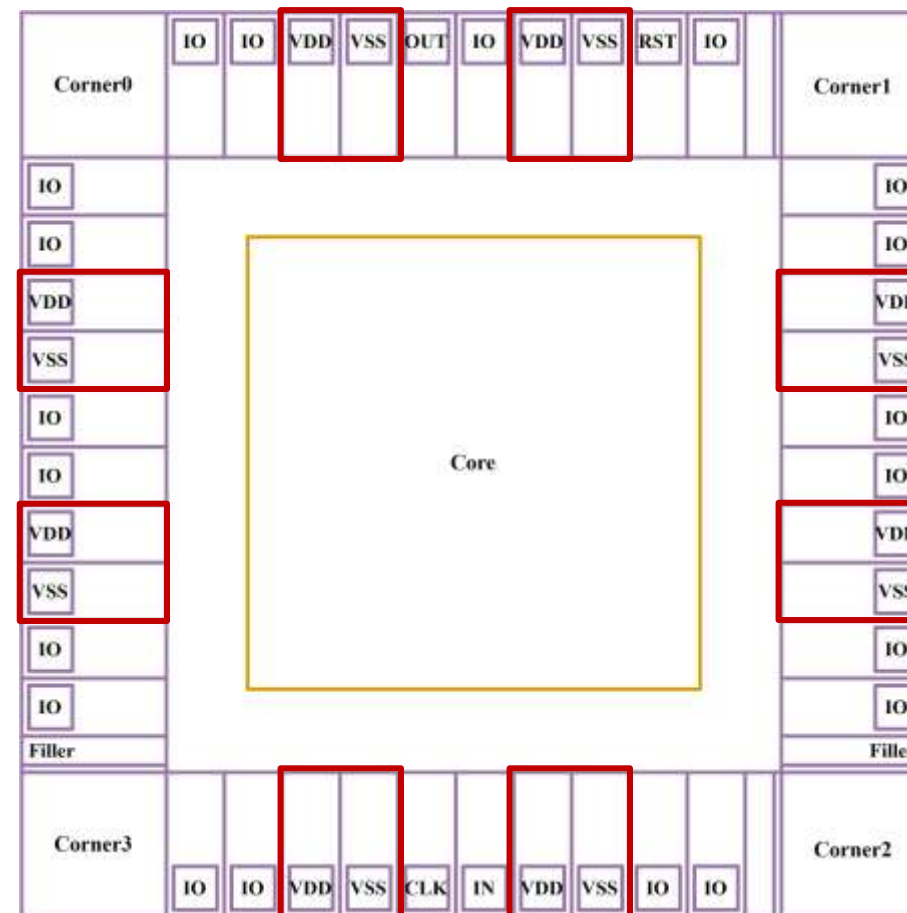
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VDD/VSS



■ init & Floorplan

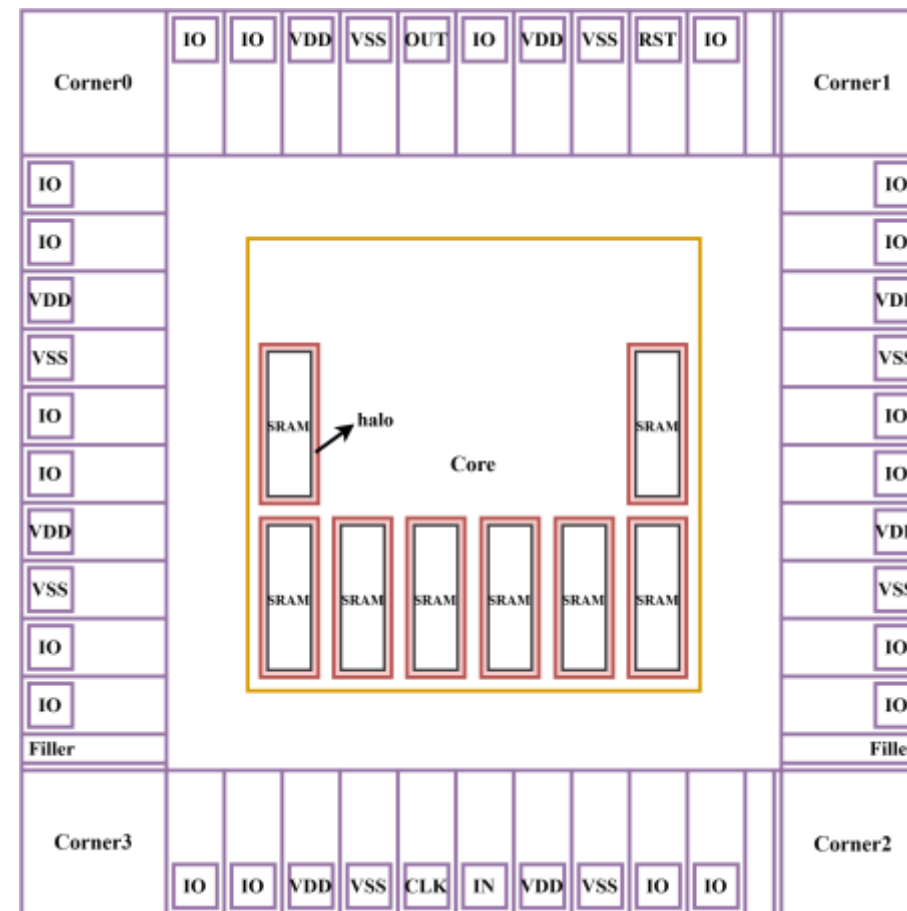
- Chip design input

- Chip I/O planning

- **Macro unit placement**

- Power supply planning

- Power ring design
- Power grid design
- Power network connection



■ init & Floorplan

- Chip design input

- Chip I/O planning

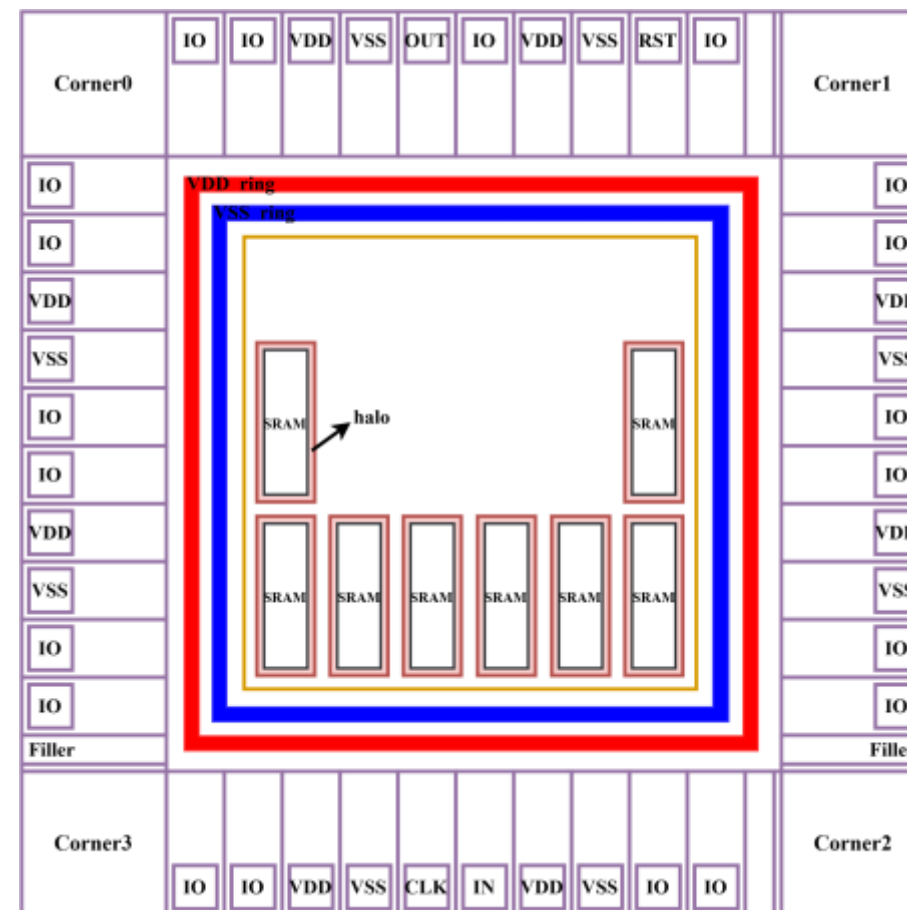
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■ init & Floorplan

- Chip design input

- Chip I/O planning

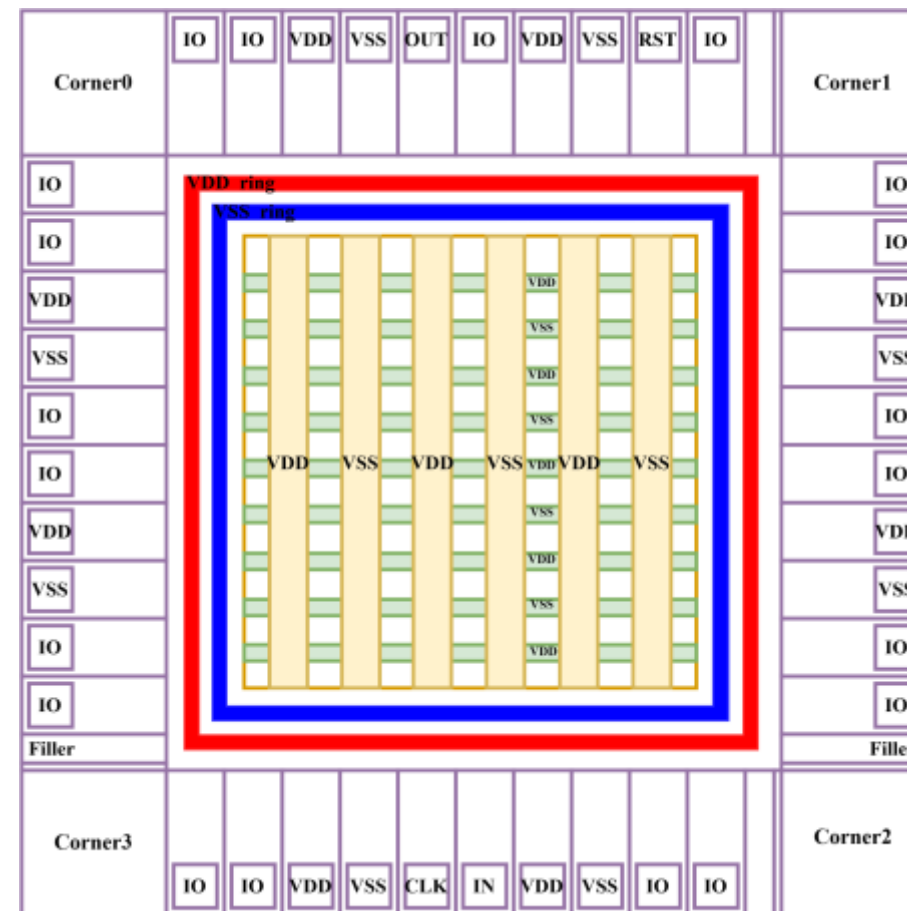
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 - Power ring design

 - **Power grid design**

 - Power network connection



■ init & Floorplan

■ Chip design input

■ Chip I/O planning

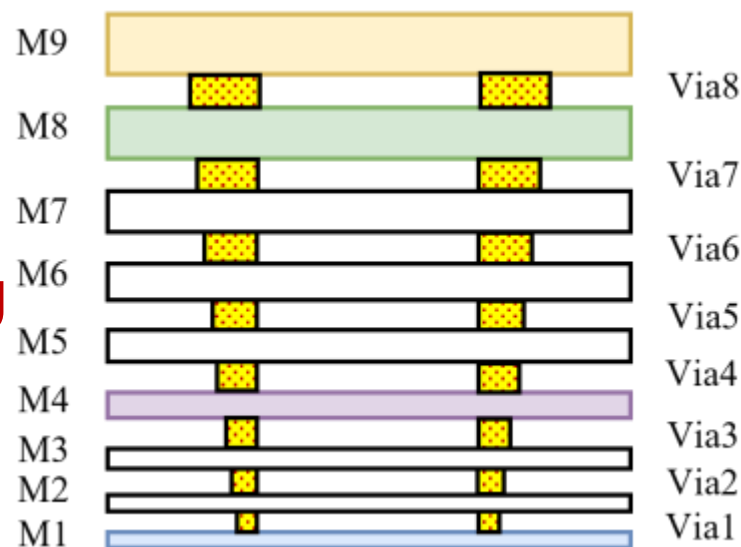
■ Macro unit placement

■ Power supply planning

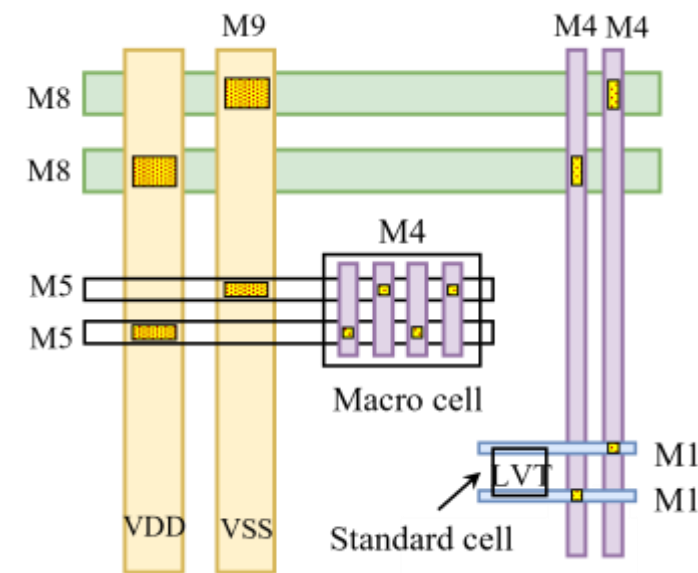
➤ Power ring design

➤ Power grid design

➤ Power network connection



Routing metal layer



Power grid

■ init & Floorplan

- Chip design input

- Chip I/O planning

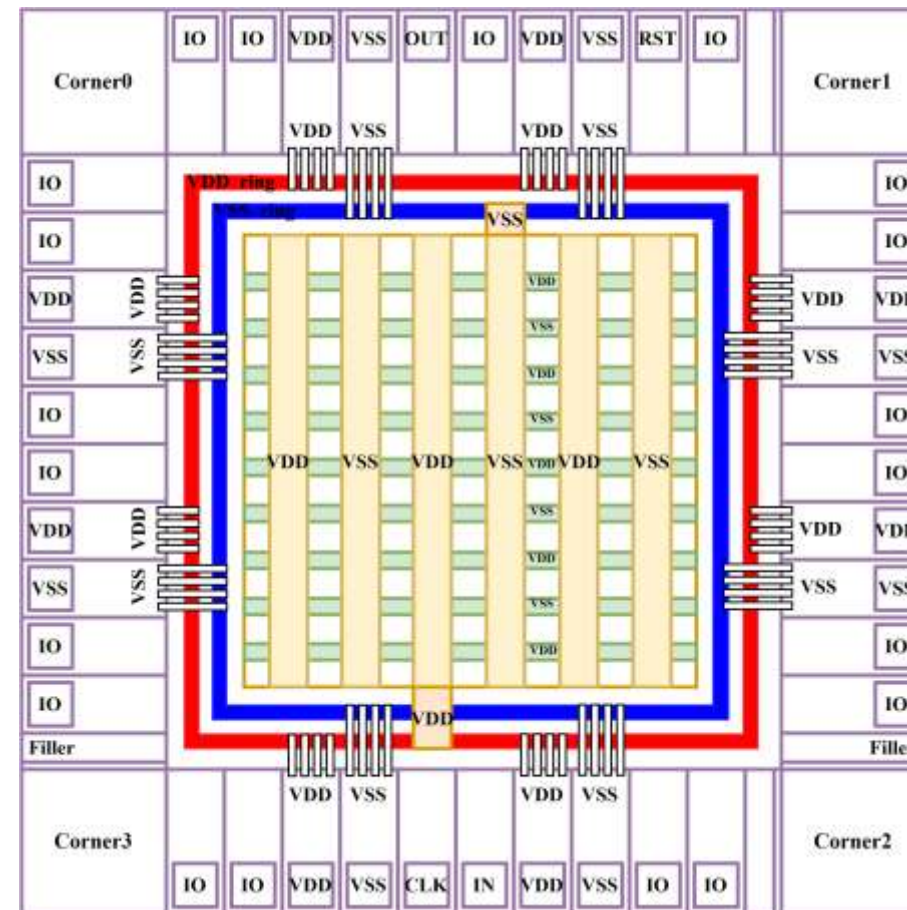
- Macro unit placement

- **Power supply planning**

 - Power ring design

 - Power grid design

 - **Power network connection**



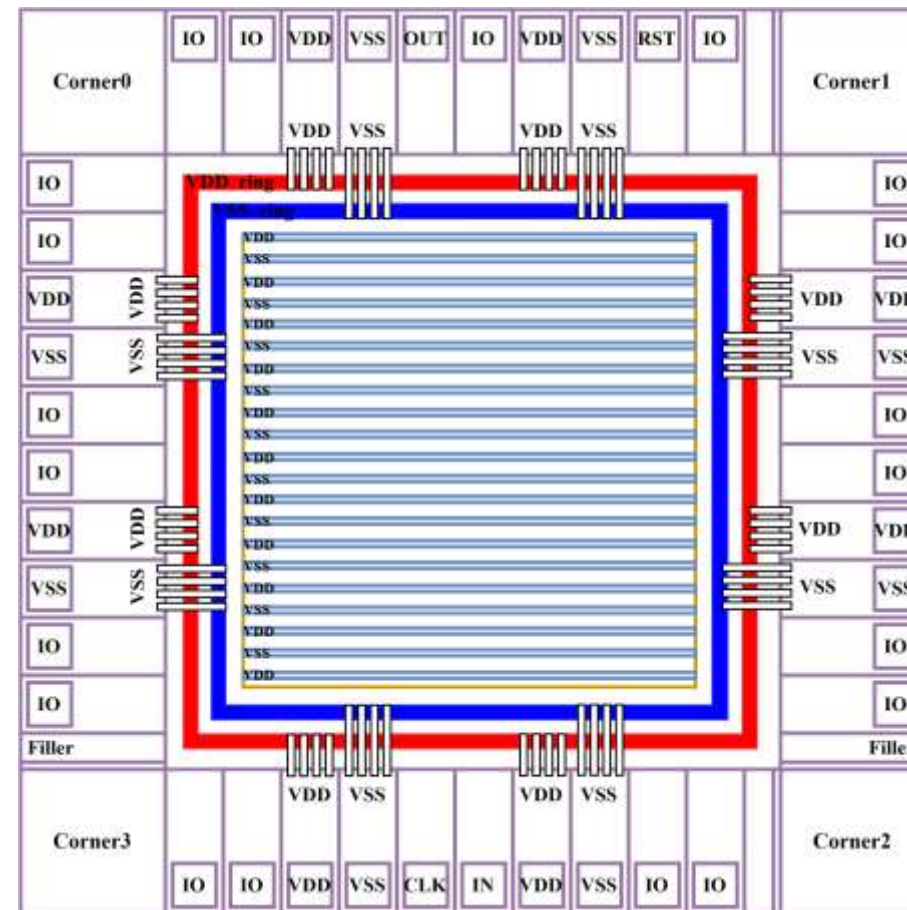
■ Place

■ The placement of standard units

- Global place
- Detail place

■ Optimization of standard units

- Whether it meets the timing sequence
- Whether it has sufficient resources



Before Place

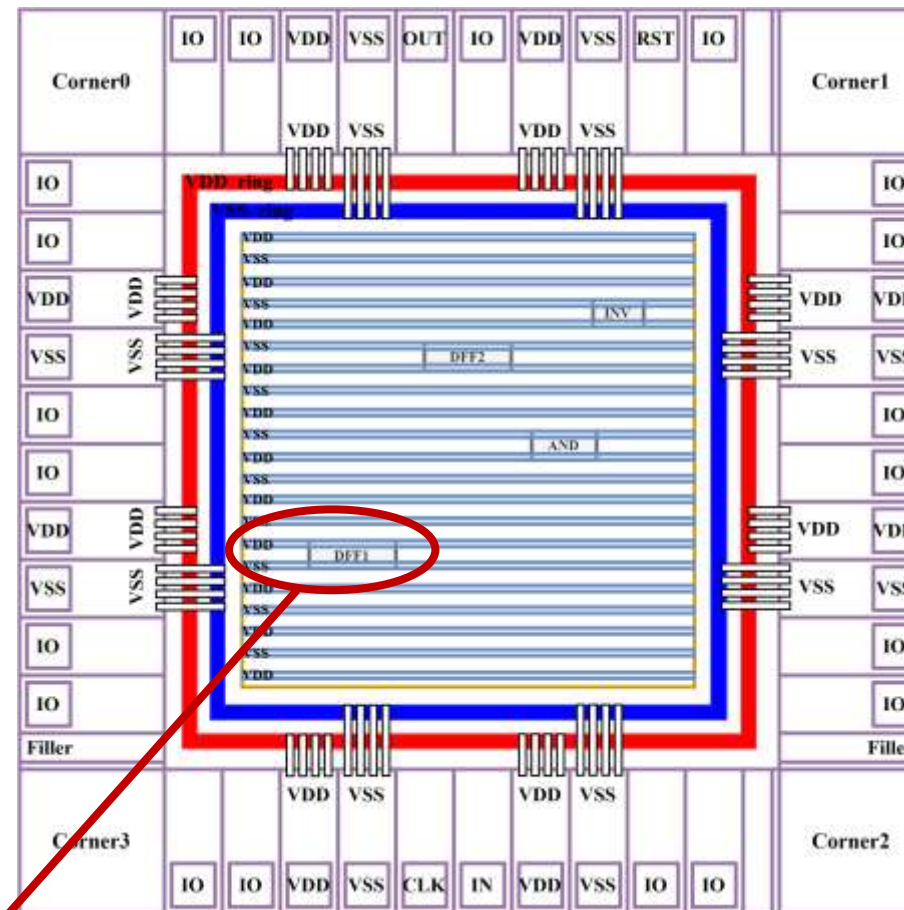
■ Place

■ The placement of standard units

- Global place
- Detail place

■ Optimization of standard units

- Whether it meets the timing sequence
- Whether it has sufficient resources



After Place

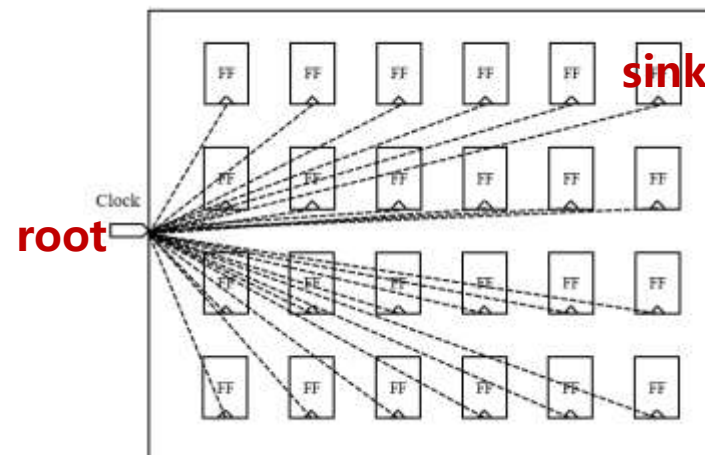
■ CTS

■ Growing clock tree

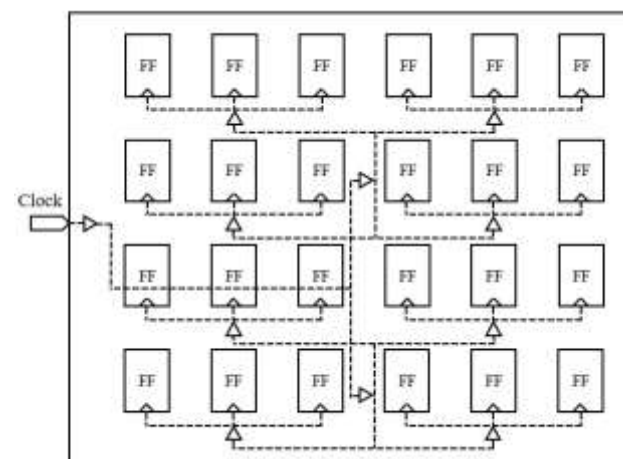
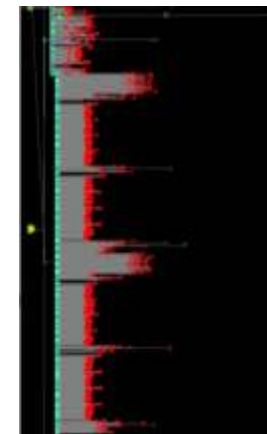
- The clock grows from the root point to each sink point
- The time skew of the clock reaching the clock terminals of each register should be as small as possible

■ Clock tree routing

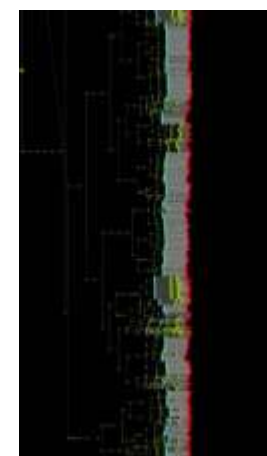
■ Optimize the timing



Before CTS



After CTS



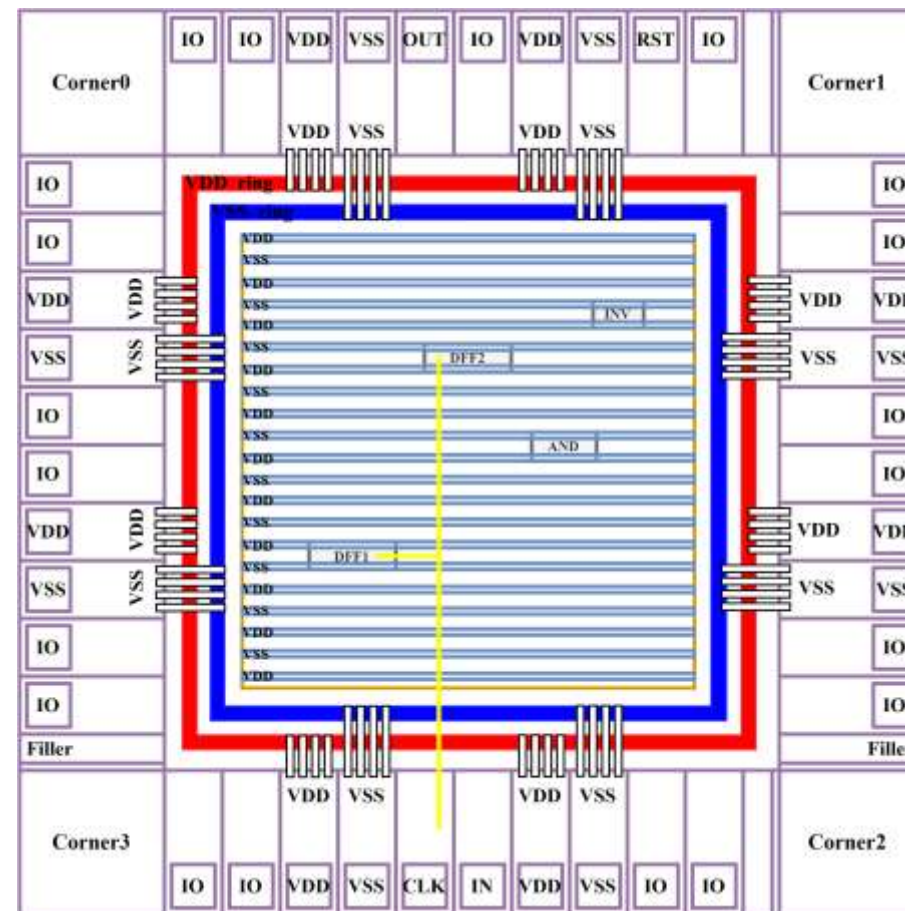
■ CTS

■ Growing clock tree

- The clock grows from the root point to each sink point
- The time skew of the clock reaching the clock terminals of each register should be as small as possible

■ Clock tree routing

■ Optimize the timing



■ Route

■ Global routing

- Plan the signal path and allocate wiring resources

■ Detail routing

- Implement the physical path to satisfy DRC

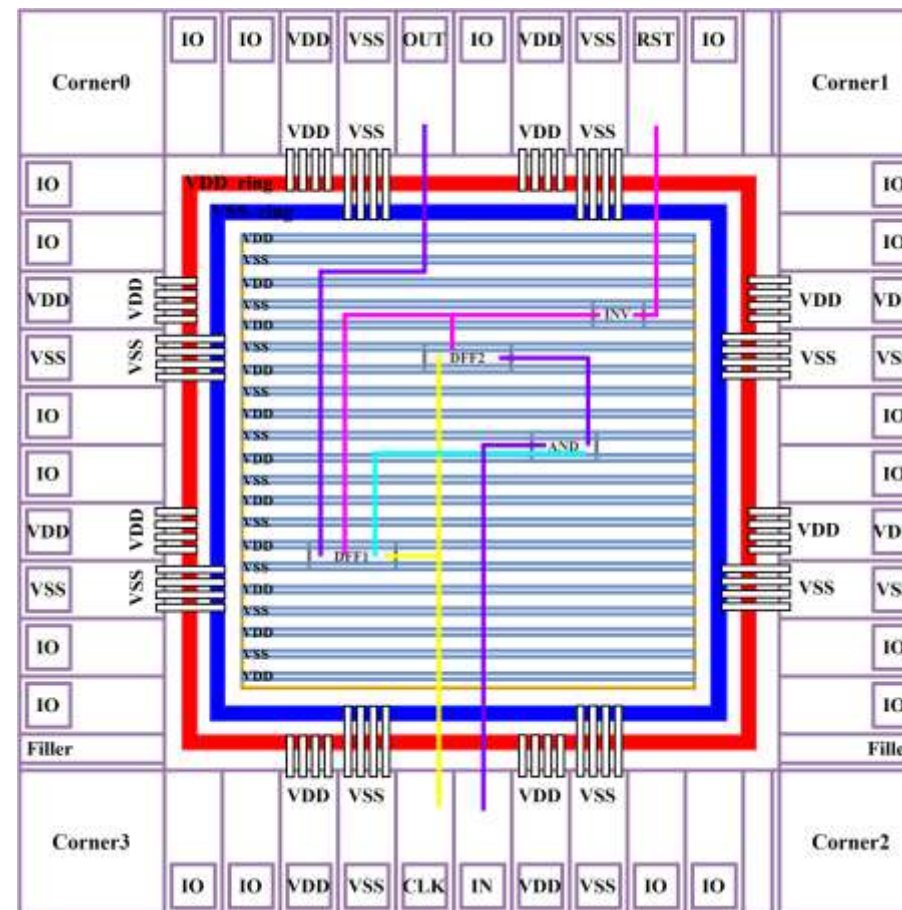
■ Search and repair

- Fix the violations after routing

■ Filler insert

■ Insert the standard Filler cell

- Connect the diffusion layer to form the power ground track



■ Route

■ Global routing

- Plan the signal path and allocate wiring resources

■ Detail routing

- Implement the physical path to satisfy DRC

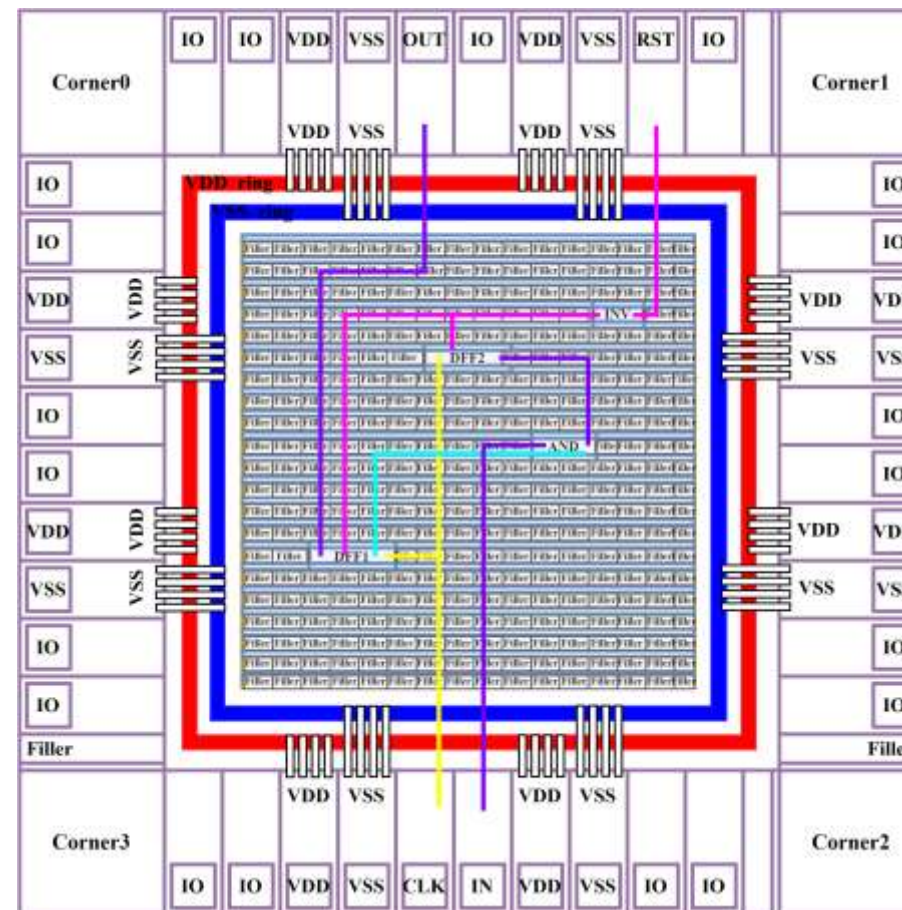
■ Search and repair

- Fix the violations after routing

■ Filler insert

■ Insert the standard Filler cell

- Connect the diffusion layer to form the power ground track



CONTENTS

1. Overview of the Back-end

2. Logical synthesis

3. Timing analysis

4. Place & Route

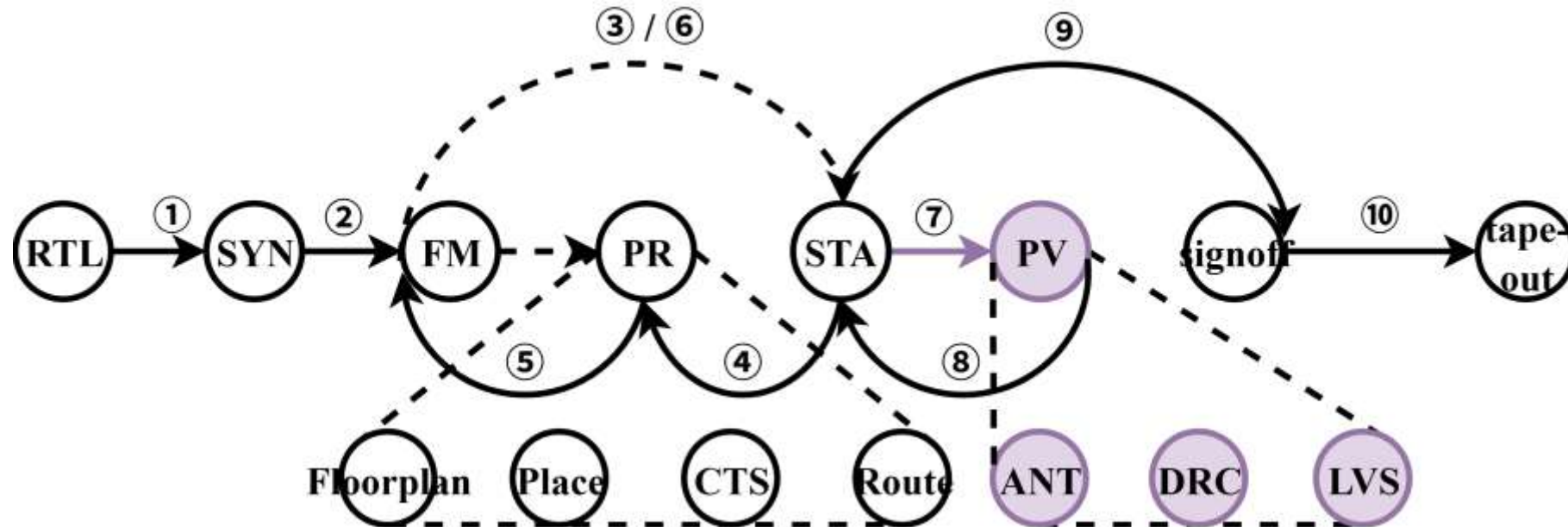
5. Physical verification

■ Physical Verification (PV)

- Electrical Rule Check (ERC)

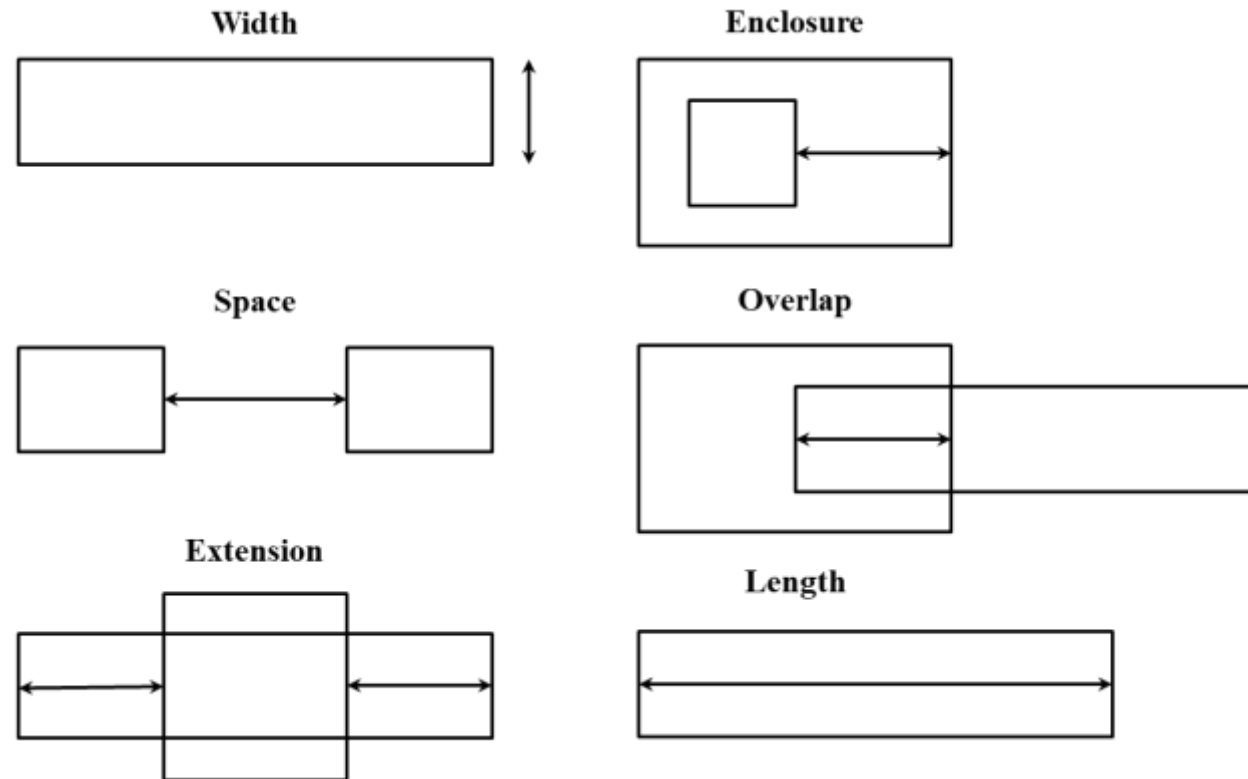
- Design Rule Check (DRC)

- Layout Versus Schematic (LVS)



■ Design Rule Check (DRC)

- Ensure that the design of the chip layout complies with the design rules provided by the wafer fab (whether it can be manufactured)



Design Rules



Thanks!